

New Claims

75. (New) A method of forming a board on chip package, comprising:
providing an insulative substrate having circuitry thereon and an opening therethrough, the substrate having a pair of opposing surfaces, the surfaces being a first surface and a second surface, the circuitry being on the first surface;

adhering a metal foil to the second surface;

adhering a semiconductive-material-comprising die to the metal foil, the die having circuitry supported thereby;

electrically connecting the circuitry supported by the die to the circuitry on the substrate with a plurality of electrical interconnects extending through the opening; and

wherein the die has a pair of opposing sides; wherein the die covers a portion of the metal foil and leaves an other portion of the metal foil extending outwardly beyond one of the opposing sides of the die; and further comprising wrapping at least some of said other portion of the foil along the at least one of the opposing sides of the die.

76. (New) The method of claim 75 wherein the die comprises a first surface facing the substrate and second surface in opposed relation to the first surface, the other portion of the foil being wrapped along both of the opposing sides of the die and over the second surface of the die.

77. (New) A method of forming a board on chip package, comprising:
providing an insulative substrate having circuitry thereon and an opening therethrough, the substrate having a pair of opposing surfaces, the surfaces being a first surface and a second surface, the circuitry being on the first surface;

adhering a metal foil to the second surface;

adhering a semiconductive-material-comprising die to the metal foil, the die having circuitry supported thereby;

electrically connecting the circuitry supported by the die to the circuitry on the substrate with a plurality of electrical interconnects extending through the opening; and

wherein the die has a pair of opposing sides; wherein the die covers a portion of the metal foil and leaves a pair of other portions of the metal foil extending outwardly beyond the opposing sides of the die; said pair of other portions comprising a first other portion which extends outwardly of the first side of the die, and a second other portion which extends outwardly of the second side of the die; the method further comprising wrapping the first other portion of the foil along the first of the opposing sides of the die, and wrapping the second other portion of the foil along the second of the opposing sides of the die.

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78. (New) The method of claim 77 wherein die comprises a first surface facing the substrate and second surface in opposed relation to the first surface, the first and second other portions of the foil joining one another over the second surface of the die.

79. (New) The method of claim 78 wherein the first and second other portions overlap one another over the second surface of the die.

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